

L Number	Hits	Search Text	DB	Time stamp
3	128	mount\$3 with system and board with electrode and (inspect\$3 detect\$3) and solder\$3 and print\$3	USPAT; EPO; JPO	2003/11/05 13:29
4	23	mount\$3 with system and board with electrode with (inspect\$3 detect\$3) and solder\$3 and print\$3	USPAT; EPO; JPO	2003/11/05 14:30
8	5	mount\$3 with system and board near2 (inspect\$3 detect\$3) with unit and electrode and solder\$3 and print\$3	USPAT; EPO; JPO	2003/11/05 14:30
-	3	(component adj1 mounting).ti. and (inoue).in.	USPAT; US-PGPUB	2003/07/11 16:02
-	838	print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3	USPAT; EPO; JPO	2003/06/26 16:10
-	747	(print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system	USPAT; EPO; JPO	2003/06/26 16:11
-	719	((print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system) and (board substrate card)	USPAT; EPO; JPO	2003/06/26 16:11
-	68	((print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system) and (board substrate card)) and 29/\$.ccls.	USPAT; EPO; JPO	2003/06/26 16:23
-	35	((print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system) and (board substrate card)) and 361/\$.ccls.	USPAT; EPO; JPO	2003/06/26 16:26
-	19	((print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system) and (board substrate card)) and 174/\$.ccls.	USPAT; EPO; JPO	2003/06/26 16:28
-	187	((print\$3 and inspect\$3 and solder\$3 and mount\$3 and controll\$3 and component and detect\$3) and system) and (board substrate card)) and electrode	USPAT; EPO; JPO	2003/06/26 16:56
-	2	print\$3 and inspect\$3 adj1 unit and (mounting mount) and pick\$3 and plac\$3 and solder\$3 and electrode	USPAT; EPO; JPO	2003/06/26 16:59
-	0	print\$3 and inspect\$3 and mounting adj1 system and pick\$3 and plac\$3 and solder\$3 and electrode	USPAT; EPO; JPO	2003/06/26 16:59
-	17	print\$3 and inspect\$3 and mounting adj1 system and electrode	USPAT; EPO; JPO	2003/06/26 17:00
-	109	component adj1 mounting with system and inspect\$3	USPAT; US-PGPUB	2003/07/11 16:03
-	75	component adj1 mounting with system and inspect\$3	USPAT; EPO; JPO	2003/07/11 16:21
-	88	component adj1 mounting and system and inspect\$3 and solder\$3 and print\$3	USPAT; EPO; JPO	2003/07/11 16:22
-	60	(component adj1 mounting and system and inspect\$3 and solder\$3 and print\$3) and control\$4	USPAT; EPO; JPO	2003/07/11 16:23
-	19	board with inspection with unit and solder\$3 and mount\$3 and controller	USPAT; EPO; JPO	2003/11/04 17:09
-	32	228/\$.ccls. and 29/\$.ccls. and component with mount\$3 with system	USPAT; EPO; JPO	2003/11/05 10:14
-	294	228/\$.ccls. and solder\$3 and component and mount\$3 with system	USPAT; EPO; JPO	2003/11/05 10:09
-	114	(228/\$.ccls. and solder\$3 and component and mount\$3 with system) and (inspect\$3 detect\$4)	USPAT; EPO; JPO	2003/11/05 10:10
-	94	solder\$3 and 29/\$.ccls. and component with mount\$3 with system and (inspect\$3 detect\$4)	USPAT; EPO; JPO	2003/11/05 10:15